

## FGD4536 360 V PDP Trench IGBT

## Features

- High Current Capability
- Low Saturation Voltage: V<sub>CE(sat)</sub> = 1.59 V @ I<sub>C</sub> = 50 A
- High Input Impedance
- Fast Switching
- RoHS Compliant

## Applications

• PDP TV, Consumer Appliances

## **General Description**

Using novel trench IGBT technology, Fairchild's new series of trench IGBTs offer the optimum performance for consumer appliances and PDP TV applications where low conduction and switching losses are essential.





## **Absolute Maximum Ratings**

Symbol	Description		Ratings	Unit		
V <sub>CES</sub>	Collector to Emitter Voltage		360	V		
V <sub>GES</sub>	Gate to Emitter Voltage		Gate to Emitter Voltage ± 3		± 30	V
I <sub>C pulse(1)*</sub>	Pulsed Collector Current @ $T_C = 25^{\circ}C$		220	A		
P <sub>D</sub>	Maximum Power Dissipation	@ T <sub>C</sub> = 25°C	125	W		
	Maximum Power Dissipation	@ T <sub>C</sub> = 100 <sup>o</sup> C	50	W		
TJ	Operating Junction Temperature		-55 to +150	°C		
T <sub>stg</sub>	Storage Temperature Range		-55 to +150	°C		
TL	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C		

## **Thermal Characteristics**

Symbol	Parameter	Тур.	Max.	Unit	
R <sub>θJC</sub> (IGBT)	Thermal Resistance, Junction to Case	-	1.0	°C/W	
$R_{\theta JA}$	A Thermal Resistance, Junction to Ambient		62.5	°C/W	

### Notes:

(1) Half Sine Wave, D < 0.01, pluse width < 1 $\mu$ sec \* lc\_pluse limited by max Tj

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## Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FGD4536	FGD4536TM	TO252(D-PAK)	380 mm	16 mm	-
FGD4536	FGD4536TM_F065	TO252(D-PAK)	380 mm	16 mm	-

## Electrical Characteristics of the IGBT T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	teristics					
BV <sub>CES</sub>	Collector to Emitter Breakdown Voltage	V <sub>GE</sub> = 0V, I <sub>C</sub> = 250 μA	360	-	-	V
$\frac{\Delta BV_{CES}}{\Delta T_{J}}$	Temperature Coefficient of Breakdown Voltage	V <sub>GE</sub> = 0V, I <sub>C</sub> = 250 μA	-	0.4	-	V/ºC
I <sub>CES</sub>	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0 V$	-	-	100	μA
I <sub>GES</sub>	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0 V$	-	-	±400	nA
On Charac	teristics					
V <sub>GE(th)</sub>	G-E Threshold Voltage	I <sub>C</sub> = 250 μA, V <sub>CE</sub> = V <sub>GE</sub>	2.4	3.3	4.0	V
0=(01)	Collector to Emitter Saturation Voltage	$I_{\rm C} = 20$ A, $V_{\rm GE} = 15$ V	-	1.19	-	V
M		I <sub>C</sub> = 30 A, V <sub>GE</sub> = 15 V	-	1.33	-	V
V <sub>CE(sat)</sub>		I <sub>C</sub> = 50 A, V <sub>GE</sub> = 15 V, T <sub>C</sub> = 25°C	-	1.59	1.8	v
		$I_{C} = 50 \text{ A}, V_{GE} = 15 \text{ V},$ $T_{C} = 125^{\circ}\text{C}$	-	1.66	-	v
Dynamic C C <sub>ies</sub>	Characteristics			1295	_	pF
C <sub>oes</sub>	Output Capacitance	V <sub>CE</sub> = 30 V <sub>,</sub> V <sub>GE</sub> = 0 V,		56	_	pF
C <sub>res</sub>	Reverse Transfer Capacitance	f = 1 MHz	_	43	-	pF
	Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time		-	5	-	ns
t <sub>r</sub>	Rise Time	V <sub>CC</sub> = 200 V, I <sub>C</sub> = 20 A, R <sub>G</sub> = 5 Ω, V <sub>GE</sub> = 15 V,	- 7	20	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	ResistiveLoad, $T_C = 25^{\circ}C$	-	41	-	ns
t <sub>f</sub>	Fall Time		-	182	- /	ns
t <sub>d(on)</sub>	Turn-On Delay Time		-	5	-	ns
t <sub>r</sub>	Rise Time	V <sub>CC</sub> = 200 V, I <sub>C</sub> = 20 A, R <sub>G</sub> = 5 Ω, V <sub>GE</sub> = 15 V,	-	21	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	Resistive Load, $T_C = 125^{\circ}C$	-	43	-	ns
	Fall Time		-	249	-	ns
чf			_	47	-	nC
t <sub>f</sub> Q <sub>g</sub>	Total Gate Charge		-	77		
	Total Gate Charge Gate to Emitter Charge	V <sub>CE</sub> = 200 V, I <sub>C</sub> = 20 A, V <sub>GE</sub> = 15 V	-	5.4	-	nC

# Typical Performance CharacteristicsFigure 1. Typical Output Characteristics











Figure 2. Typical Output Characteristics



Figure 4. Transfer Characteristics







30

1000





Collector-Emitter Voltage, V<sub>CE</sub> [V]





### **Mechanical Dimensions** A 6.73 6.35 5.46 6.00 MIN-1.27 6.50 MIN 6.22 5.97 1.02 MAX 6.25 11 C 2 1 Т 2 + 3.00 MIN 3 (0.59) 0.76 1.40 MIN 2.30 0.89 2.29 ⊕ 0.25 ( A ( C 4.60 4.57 LAND PATTERN RECOMMENDATION В SEE NOTE D 2.39 4.32 MIN Δ 0.58 MIN 5.21 SEE 10.41 9.40 DETAIL A 2 3 0.10 B 0.51 GAGE PLANE NOTES: UNLESS OTHERWISE SPECIFIED A) THIS PACKAGE CONFORMS TO JEDEC, TO-252, ISSUE C, VARIATION AA. B) ALL DIMENSIONS ARE IN MILLIMETERS. 0.61 (1.54) 10 ALL DIMENSIONS ARE IN MILLIMETERS. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994. HEAT SINK TOP EDGE COULD BE IN CHAMFERED CORNERS OR EDGE PROTRUSION. PRESENCE OF TRIMMED CENTER LEAD c) D) E) 1.78 0.127 MAX IS OPTIONAL IS OPTIONAL. DIMENSIONS ARE EXCLUSSIVE OF BURSS, MOLD FLASH AND TIE BAR EXTRUSIONS. LAND PATTERN RECOMENDATION IS BASED ON IPC7351A STD T0220P1003X238-3N. F) SEATING PLANE (2.90) G) DETAIL A (ROTATED -90°) SCALE: 12X DRAWING NUMBER AND REVISION: MKT-T0252A03REV8 H) Figure 19. TO252 (D-PAK), MOLDED, 3 LEAD, OPTION AA&AB

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Dimensions in Millimeters



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